



## LTM9001 81LD 11.25mm X 11.25mm X 2.32mm (TABLE OF MATERIAL DECLARATION)

***The LTM9001 is RoHS compliant per EU RoHS Directive 2003/95/EC.***

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1624	Barium Compounds	7727-43-7	0.0024	1.5000
				Filler Substances (Silica Crystalline)	-	0.0648	39.9146
				Copper Metal	7440-50-8	0.0909	56.0000
				Copper Compounds	1328-53-6	0.0000	0.0180
				Ecotoxic substances	7439-92-1	0.0000	0.0004
				Gold metal or alloy	7440-57-5	0.0007	0.4600
				Nickel	7440-02-0	0.0034	2.1000
				Zinc	7440-66-6	0.0000	0.0070
2	Solder Paste	Alloy	0.0077	Sn	7440-31-5	0.0073	95.0000
				Sb	7440-36-0	0.0004	5.0000
3	Passive/Active Components		0.0301	Capacitor	-	0.0269	89.2134
				Resistor	-	0.0013	4.3246
				Inductor	-	0.0019	6.4520
				Diode	-	0.0000	0.0000
4	Active Ics	Silicon	0.0067	Silicon	7440-21-3	0.0067	100.0000
5	Wire	Gold	0.0013	Au	7440-57-5	0.0013	99.9900
6	LTC6400IUD	see LTC web site for material declaration	0.0205			0.0205	100.0000
7	Encapsulation	Epoxy Resin	0.4749	Fused Silica	60676-86-0	0.3666	77.2000
				Epoxy Resin	-	0.0423	8.9000
				Phenol Resin	-	0.0423	8.9000
				Crytalline Silica	14808-60-7	0.0142	3.0000
				Carbon Black	1333-86-4	0.0024	0.5000
				Metal Hydroxide	-	0.0071	1.5000
Total Package Weight			0.7037				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts